L Number	Hits		DB	Time stamp
_	1	(knife adj ring) near (movable or moveable	USPAT;	2004/09/22 10:02
		or positionable)	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	204	knife adj ring	USPAT;	2004/09/20 11:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	(("15156.DID.").PN.) and (wafer or	IBM_TDB	0004/00/00
		semiconductor)	USPAT;	2004/09/20 12:00
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	1
-	9	(knife adj ring) and (wafer or	USPAT;	2004/09/20 12:03
		semiconductor)	US-PGPUB;	2001,03,20 12.03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	233	134/149.ccls.	USPAT;	2004/09/20 12:03
			US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
_	46	134/149.ccls. and (wafer or semiconductor)	IBM TDB	0004/00/00
	40	107/149.0018. and (water or semiconductor)	USPAT; US-PGPUB;	2004/09/20 12:16
		,	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
_	650	134/184.ccls.	USPAT;	2004/09/20 12:16
			US-PGPUB;	2001,03,20 12.10
	•		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	212	134/184.ccls. and (wafer or semiconductor)	USPAT;	2004/09/20 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	717	134/186.ccls.	IBM_TDB USPAT;	2004/09/20 12:24
	/ - '	151/100.0015.	US-PGPUB;	2004/09/20 12:24
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	151	134/186.ccls. and (wafer or semiconductor)	USPAT;	2004/09/20 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	9	(124/106	IBM_TDB	
	9	(134/186.ccls. and (wafer or	USPAT;	2004/09/20 12:25
		semiconductor)) and knife	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	- 5	(air adj knife) near (movable or moveable	IBM_TDB USPAT;	2004/09/22 10:03
	_	or positionable)	US-PGPUB;	2004/03/22 10:03
	İ	, ·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	134	(air adj knife) same (movable or moveable	USPAT;	2004/09/22 10:11
-		or positionable)	US-PGPUB;	
ļ			EPO; JPO;	
			DERWENT;	
_ ,	1540045	unfor an arminum dest	IBM_TDB	
-	1540045	wafer or semiconductor	USPAT;	2004/09/22 10:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

	20	((air adj knife) same (movable or moveable or positionable)) and (wafer or semiconductor)	USPAT; US-PGPUB;	2004/09/22 10:14
		or positionable // and (water or		
		I Semi conductori	LEDO. TDO.	
		- Some Some Coly	EPO; JPO; DERWENT;	
			IBM TDB	
_	296	134/148.ccls.	USPAT;	2004/09/22 10:14
			US-PGPUB;	2004/03/22 10.14
			EPO; JPO;	
		· ·	DERWENT;	
			IBM TDB	
-	65	134/148.ccls. and (wafer or semiconductor)	USPĀT;	2004/09/22 10:30
			US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
l _	797	134/153.ccls.	IBM_TDB	
	191	134/133.6618.	USPAT;	2004/09/22 10:30
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	6	(134/153.ccls. and (wafer or	USPAT;	2004/09/22 10:31
	_	semiconductor)) and (air same ((backside	US-PGPUB;	2004/09/22 10:31
		or underside) near wafer))	EPO; JPO;	
		× ''	DERWENT;	
			IBM TDB	
-	291	134/153.ccls. and (wafer or semiconductor)	USPĀT;	2004/09/22 10:43
ļ			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	171	124/154	IBM_TDB	
-	171	134/154.ccls.	USPAT;	2004/09/22 11:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2190	134/902.ccls.	IBM_TDB USPAT;	2004/09/22 11:38
	1 2130	131/302.0013.	US-PGPUB;	2004/09/22 11:38
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
- '	37	134/902.ccls. and (air adj knife)	USPAT;	2004/09/22 11:48
			US-PGPUB;	İ
			EPO; JPO;	
1	i		DERWENT;	
			IBM_TDB	
_		air adj ((nozzle or jet or knife) same	USPAT;	2004/09/22 11:49
		(wafer near backside))	US-PGPUB;	
, !			EPO; JPO;	
			DERWENT; IBM TDB	
	11	air same ((nozzle or jet or knife) same	USPAT;	2004/09/22 11:53
		(wafer near backside))	US-PGPUB;	2004/03/22 11:33
		,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
~	9711	"taiwan semiconductor".as.	USPĀT;	2004/09/22 11:54
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_		Headanna and and a second	IBM_TDB	
-	3	"taiwan semiconductor".as. and (knife same	USPAT;	2004/09/22 11:55
		ring)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1540045	wafer or semiconductor	IBM_TDB USPAT;	2004/00/20 10:04
			US-PGPUB;	2004/09/20 12:04
			OD LOEUD,	1
			EPO: JPO:	l
			EPO; JPO; DERWENT;	

_	1540045	wafer or semiconductor	TICDAM.	1000110010
		water of semiconductor	USPAT;	2004/09/22 13:23
			US-PGPUB;	İ
			EPO; JPO;	
			DERWENT;	
	026056	,, ,,	IBM_TDB	
_	236056	(knife adj edge) or (knife adj ring) or divider	USPAT;	2004/09/22 13:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	11653	((knife adj edge) or (knife adj ring) or	USPAT;	2004/09/22 13:25
		divider) same (backside or rear or (back	US-PGPUB;	1, 55, 22 13.25
		adj side) or reverse)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1755225	((knife adj edge) or (knife adj ring) or	USPAT;	2004/09/22 13:26
		divider) same (backside or rear or (back	US-PGPUB;	2004/03/22 13:26
		adj side) or reverse) near[25] (adjustable	EPO; JPO;	
		or movable or moveable or positionable)	DERWENT;	l i
		or movemble of positionable)	1	
_	1265	(wafer or semiconductor) and (((knife ad)	IBM_TDB	0004/00/00 55 55
	1 +200	edge) or (knife adj ring) or divider) same	USPAT;	2004/09/22 13:27
		(backside or room on (backside)	US-PGPUB;	
		(backside or rear or (back adj side) or	EPO; JPO;	
		reverse))	DERWENT;	
	5	//:::5	IBM_TDB	
	5	((wafer or semiconductor) and (((knife adj	USPAT;	2004/09/22 13:27
		edge) or (knife adj ring) or divider) same	US-PGPUB;	
		(backside or rear or (back adj side) or	EPO; JPO;	
		reverse))) and 134/\$.ccls.	DERWENT;	
			IBM TDB	